

PROBE CARD, E.G., FOR TESTING MICROELECTRONIC COMPONENTS, AND  
METHODS FOR MAKING SAME

ABSTRACT OF THE DISCLOSURE

Various aspects of the invention provide methods of manufacturing probe cards and test systems which may test microelectronic components using such probe cards. In one specific example, a probe card may be manufactured by forming a plurality of blind holes in a substrate, with each hole having a closed bottom spaced from a back of the substrate by a back thickness. An electrically conductive metal may be deposited on the substrate to fill the holes and define an overburden on the substrate. The metal in each hole may define a conductor. At least a portion of the overburden may be removed to electrically isolate each of the conductors from one another. A portion of the substrate including the back thickness is removed to define an array of pins extending outwardly from a remaining thickness of the substrate, with each pin being an exposed length of one of the conductors.